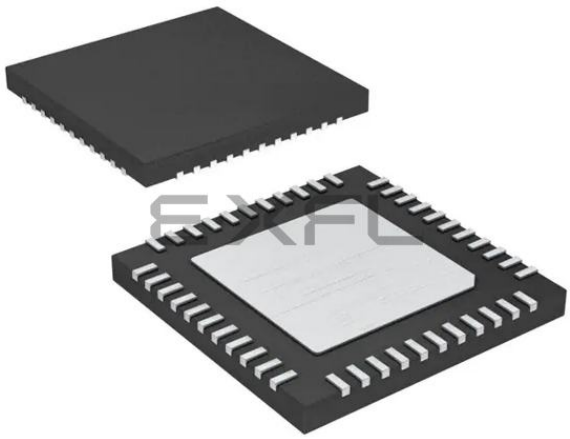

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	36
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 14x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f724t-i-ml

TABLE 1: 28-PIN PDIP/SOIC/SSOP/QFN/UQFN SUMMARY (PIC16F722/723/726/PIC16LF722/723/726)

I/O	28-Pin PDIP, SOIC, SSOP	28-Pin QFN, UQFN	A/D	Cap Sensor	Timers	CCP	AUSART	SSP	Interrupt	Pull-Up	Basic
RA0	2	27	AN0	—	—	—	—	$\overline{SS}$(3)	—	—	VCAP(4)
RA1	3	28	AN1	—	—	—	—	—	—	—	—
RA2	4	1	AN2	—	—	—	—	—	—	—	—
RA3	5	2	AN3/VREF	—	—	—	—	—	—	—	—
RA4	6	3	—	CPS6	T0CKI	—	—	—	—	—	—
RA5	7	4	AN4	CPS7	—	—	—	$\overline{SS}$(3)	—	—	VCAP(4)
RA6	10	7	—	—	—	—	—	—	—	—	OSC2/CLKOUT/VCAP(4)
RA7	9	6	—	—	—	—	—	—	—	—	OSC1/CLKIN
RB0	21	18	AN12	CPS0	—	—	—	—	IOC/INT	Y	—
RB1	22	19	AN10	CPS1	—	—	—	—	IOC	Y	—
RB2	23	20	AN8	CPS2	—	—	—	—	IOC	Y	—
RB3	24	21	AN9	CPS3	—	CCP2(2)	—	—	IOC	Y	—
RB4	25	22	AN11	CPS4	—	—	—	—	IOC	Y	—
RB5	26	23	AN13	CPS5	T1G	—	—	—	IOC	Y	—
RB6	27	24	—	—	—	—	—	—	IOC	Y	ICSPCLK/ICDCLK
RB7	28	25	—	—	—	—	—	—	IOC	Y	ICSPDAT/ICDDAT
RC0	11	8	—	—	T1OSO/T1CKI	—	—	—	—	—	—
RC1	12	9	—	—	T1OSI	CCP2(2)	—	—	—	—	—
RC2	13	10	—	—	—	CCP1	—	—	—	—	—
RC3	14	11	—	—	—	—	—	SCK/SCL	—	—	—
RC4	15	12	—	—		—	—	SDI/SDA	—	—	—
RC5	16	13	—	—	—	—	—	SDO	—	—	—
RC6	17	14	—	—	—	—	TX/CK	—	—	—	—
RC7	18	15	—	—	—	—	RX/DT	—	—	—	—
RE3	1	26	—	—	—	—	—	—	—	Y(1)	$\overline{MCLR}$/VPP
—	20	17	—	—	—	—	—	—	—	—	VDD
—	8,19	5,16	—	—	—	—	—	—	—	—	VSS

Note 1: Pull-up enabled only with external $\overline{MCLR}$ Configuration.
2: RC1 is the default pin location for CCP2. RB3 may be selected by changing the CCP2SEL bit in the APFCON register.
3: RA5 is the default pin location for $\overline{SS}$. RA0 may be selected by changing the SSSEL bit in the APFCON register.
4: PIC16F724/727/PIC16LF724/727 devices only.

Note: The PIC16F722/3/4/6/7 devices have an internal low dropout voltage regulator. An external capacitor must be connected to one of the available VCAP pins to stabilize the regulator. For more information, see **Section 5.0 "Low Dropout (LDO) Voltage Regulator"**. The PIC16LF722/3/4/6/7 devices do not have the voltage regulator and therefore no external capacitor is required.

3.6 Time-out Sequence

On power-up, the time-out sequence is as follows: first, PWRT time out is invoked after POR has expired, then OST is activated after the PWRT time out has expired. The total time out will vary based on oscillator configuration and $\overline{\text{PWRTE}}$ bit status. For example, in EC mode with $\overline{\text{PWRTE}}$ bit = 1 (PWRT disabled), there will be no time out at all. Figure 3-4, Figure 3-5 and Figure 3-6 depict time-out sequences.

Since the time outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time outs will expire. Then, bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 3-5). This is useful for testing purposes or to synchronize more than one PIC16(L)F722/3/4/6/7 device operating in parallel.

Table 3-3 shows the Reset conditions for some special registers.

3.7 Power Control (PCON) Register

The Power Control (PCON) register has two Status bits to indicate what type of Reset that last occurred.

Bit 0 is $\overline{\text{BOR}}$ (Brown-out Reset). $\overline{\text{BOR}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent Resets to see if $\overline{\text{BOR}}$ = 0, indicating that a brown-out has occurred. The $\overline{\text{BOR}}$ Status bit is a “don’t care” and is not necessarily predictable if the brown-out circuit is disabled (BOREN<1:0> = 00 in the Configuration Word register).

Bit 1 is $\overline{\text{POR}}$ (Power-on Reset). It is a ‘0’ on Power-on Reset and unaffected otherwise. The user must write a ‘1’ to this bit following a Power-on Reset. On a subsequent Reset, if $\overline{\text{POR}}$ is ‘0’, it will indicate that a Power-on Reset has occurred (i.e., V_{DD} may have gone too low).

For more information, see **Section 3.5 “Brown-Out Reset (BOR)”**.

TABLE 3-2: TIME OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset		Wake-up from Sleep
	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1	
XT, HS, LP(1)	T_{PWRT} + 1024 • T_{OSC}	1024 • T_{OSC}	T_{PWRT} + 1024 • T_{OSC}	1024 • T_{OSC}	1024 • T_{OSC}
RC, EC, INTOSC	T_{PWRT}	—	T_{PWRT}	—	—

Note 1: LP mode with T1OSC disabled.

TABLE 3-3: RESET BITS AND THEIR SIGNIFICANCE

$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	u	1	1	Power-on Reset
1	0	1	1	Brown-out Reset
u	u	0	u	WDT Reset
u	u	0	0	WDT Wake-up
u	u	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
u	u	1	0	$\overline{\text{MCLR}}$ Reset during Sleep

Legend: u = unchanged, x = unknown

6.2 PORTA and the TRISA Registers

PORTA is a 8-bit wide, bidirectional port. The corresponding data direction register is TRISA (Register 6-3). Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input (i.e., disable the output driver). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output (i.e., enables output driver and puts the contents of the output latch on the selected pin). Example 6-1 shows how to initialize PORTA.

Reading the PORTA register (Register 6-2) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch.

The TRISA register (Register 6-3) controls the PORTA pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISA register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

Note:	The ANSELA register must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'.

EXAMPLE 6-1: INITIALIZING PORTA

```
BANKSEL PORTA       ;
CLRF    PORTA       ;Init PORTA
BANKSEL ANSELA      ;
CLRF    ANSELA      ;digital I/O
BANKSEL TRISA       ;
MOVLW   0Ch         ;Set RA<3:2> as inputs
MOVWF   TRISA       ;and set RA<7:4,1:0>
                    ;as outputs
```

REGISTER 6-2: PORTA: PORTA REGISTER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **RA<7:0>**: PORTA I/O Pin bit
1 = Port pin is > V_{IH}
0 = Port pin is < V_{IL}

REGISTER 6-3: TRISA: PORTA TRI-STATE REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **TRISA<7:0>:** PORTA Tri-State Control bit
1 = PORTA pin configured as an input (tri-stated)
0 = PORTA pin configured as an output

6.2.1 ANSELA REGISTER

The ANSELA register (Register 6-4) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELA bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELA bits has no affect on digital output functions. A pin with TRIS clear and ANSEL set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

REGISTER 6-4: ANSELA: PORTA ANALOG SELECT REGISTER

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **ANSA<5:0>**: Analog Select between Analog or Digital Function on pins RA<5:0>, respectively

0 = Digital I/O. Pin is assigned to port or Digital special function.

1 = Analog input. Pin is assigned as analog input**(1)**. Digital Input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

FIGURE 6-8: BLOCK DIAGRAM OF RB4, RB<2:1>

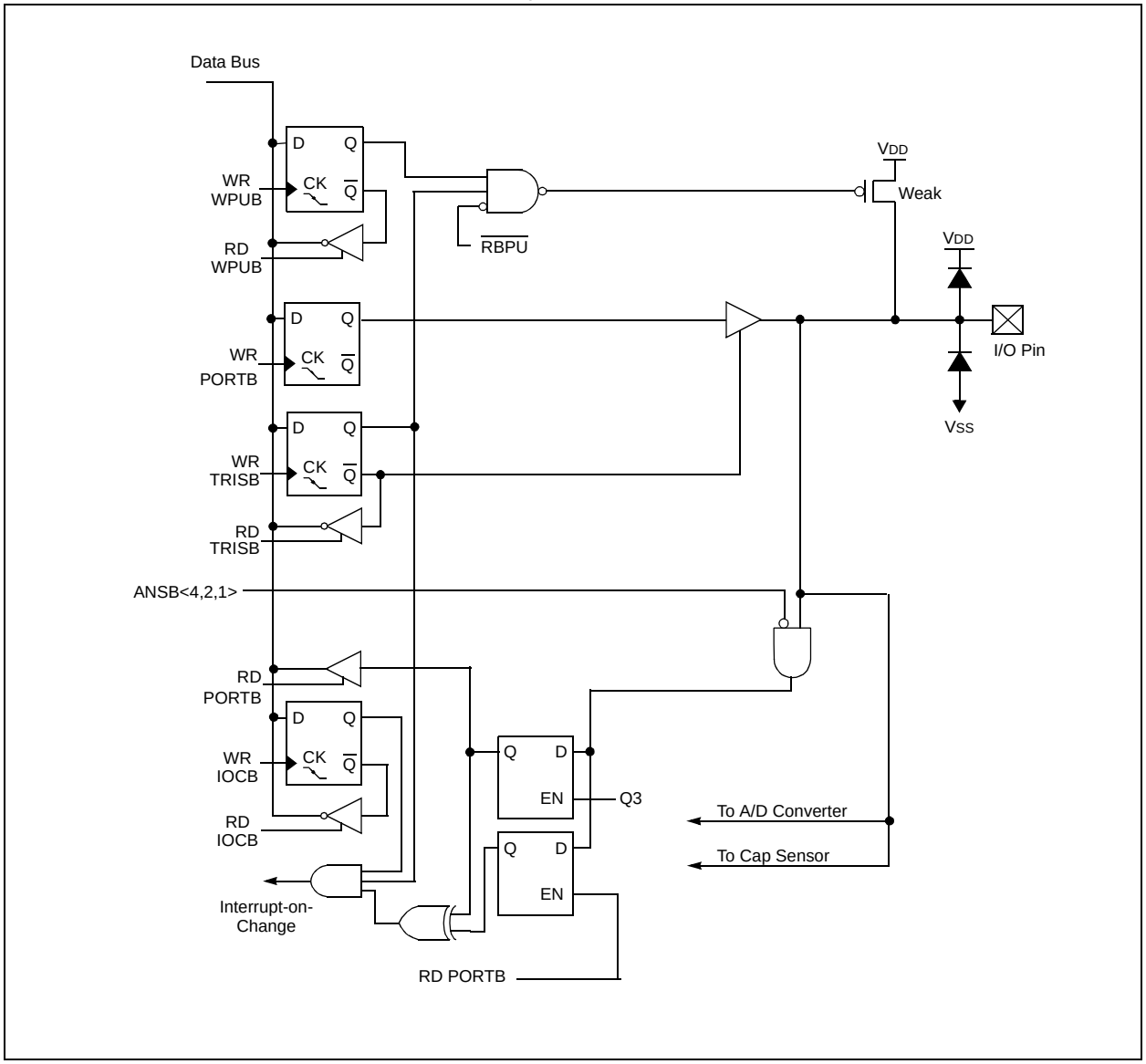


FIGURE 6-19: BLOCK DIAGRAM OF RC6

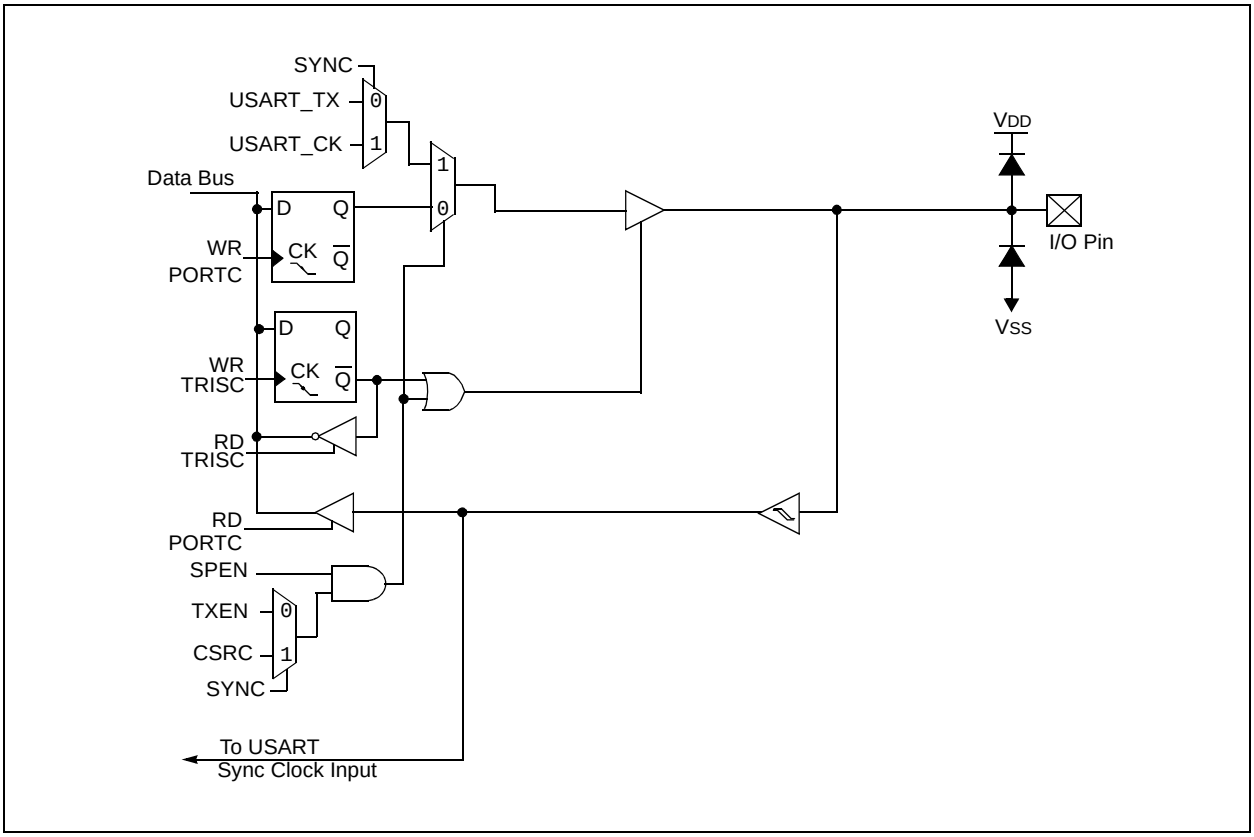
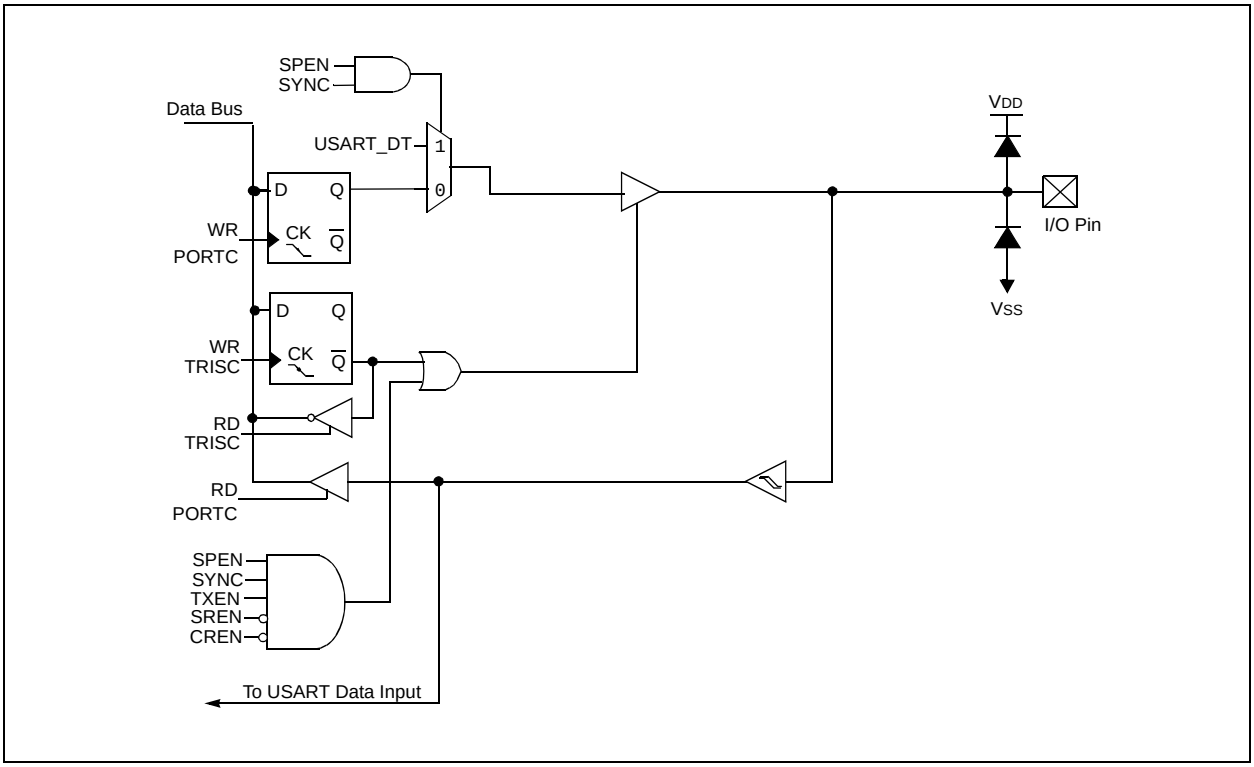


FIGURE 6-20: BLOCK DIAGRAM OF RC7



REGISTER 6-15: PORTE: PORTE REGISTER

U-0	U-0	U-0	U-0	R-x	R/W-x	R/W-x	R/W-x
—	—	—	—	RE3	RE2(1)	RE1(1)	RE0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-4 **Unimplemented**: Read as '0'

bit 3-0 **RE<3:0>**: PORTE I/O Pin bits(1)
1 = Port pin is > VIH
0 = Port pin is < VIL

Note 1: RE<2:0> are not implemented on the PIC16F722/723/726/PIC16LF722/723/726. Read as '0'.

REGISTER 6-16: TRISE: PORTE TRI-STATE REGISTER

U-0	U-0	U-0	U-0	R-1	R/W-1	R/W-1	R/W-1
—	—	—	—	TRISE3	TRISE2(1)	TRISE1(1)	TRISE0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-4 **Unimplemented**: Read as '0'

bit 3 **TRISE3:** RE3 Port Tri-state Control bit
This bit is always '1' as RE3 is an input only

bit 2-0 **TRISE<2:0>:** RE<2:0> Tri-State Control bits(1)
1 = PORTE pin configured as an input (tri-stated)
0 = PORTE pin configured as an output

Note 1: TRISE<2:0> are not implemented on the PIC16F722/723/726/PIC16LF722/723/726. Read as '0'.

9.3 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 9-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 9-3. **The maximum recommended impedance for analog sources is 10 kΩ**. As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 9-1 may be used. This equation assumes that 1/2 LSb error is used (256 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 9-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ $5.0V$ V_{DD}

$$\begin{aligned} T_{ACQ} &= \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient} \\ &= T_{AMP} + T_C + T_{COFF} \\ &= 2\mu s + T_C + [(\text{Temperature} - 25°C)(0.05\mu s/°C)] \end{aligned}$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD} \text{ charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD} \text{ charge response to } V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) \quad ;\text{combining [1] and [2]}$$

Note: *Where n = number of bits of the ADC.*

Solving for T_C*:*

$$\begin{aligned} T_C &= -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/511) \\ &= -10pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.001957) \\ &= 1.12\mu s \end{aligned}$$

Therefore:

$$\begin{aligned} T_{ACQ} &= 2MS + 1.12MS + [(50°C - 25°C)(0.05MS/°C)] \\ &= 4.42MS \end{aligned}$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

11.1.3 SOFTWARE PROGRAMMABLE PRESCALER

A single software programmable prescaler is available for use with either Timer0 or the Watchdog Timer (WDT), but not both simultaneously. The prescaler assignment is controlled by the PSA bit of the OPTION register. To assign the prescaler to Timer0, the PSA bit must be cleared to a '0'.

There are eight prescaler options for the Timer0 module ranging from 1:2 to 1:256. The prescale values are selectable via the PS<2:0> bits of the OPTION register. In order to have a 1:1 prescaler value for the Timer0 module, the prescaler must be assigned to the WDT module.

The prescaler is not readable or writable. When assigned to the Timer0 module, all instructions writing to the TMR0 register will clear the prescaler.

Note:	When the prescaler is assigned to WDT, a CLRWDT instruction will clear the prescaler along with the WDT.

11.1.4 TIMER0 INTERRUPT

Timer0 will generate an interrupt when the TMR0 register overflows from FFh to 00h. The T0IF interrupt flag bit of the INTCON register is set every time the TMR0 register overflows, regardless of whether or not the Timer0 interrupt is enabled. The T0IF bit can only be cleared in software. The Timer0 interrupt enable is the T0IE bit of the INTCON register.

Note:	The Timer0 interrupt cannot wake the processor from Sleep since the timer is frozen during Sleep.

11.1.5 8-BIT COUNTER MODE SYNCHRONIZATION

When in 8-Bit Counter mode, the incrementing edge on the T0CKI pin must be synchronized to the instruction clock. Synchronization can be accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the instruction clock. The high and low periods of the external clocking source must meet the timing requirements as shown in **Section 23.0 "Electrical Specifications"**.

17.2.2 START AND STOP CONDITIONS

During times of no data transfer (Idle time), both the clock line (SCL) and the data line (SDA) are pulled high through external pull-up resistors. The Start and Stop conditions determine the start and stop of data transmission. The Start condition is defined as a high-to-low transition of the SDA line while SCL is high. The Stop condition is defined as a low-to-high transition of the SDA line while SCL is high.

Figure 17-9 shows the Start and Stop conditions. A master device generates these conditions for starting and terminating data transfer. Due to the definition of the Start and Stop conditions, when data is being transmitted, the SDA line can only change state when the SCL line is low.

17.2.3 ACKNOWLEDGE

After the valid reception of an address or data byte, the hardware automatically will generate the Acknowledge ($\overline{ACK}$) pulse and load the SSPBUF register with the received value currently in the SSPSR register. There are certain conditions that will cause the SSP module not to generate this $\overline{ACK}$ pulse. They include any or all of the following:

- The Buffer Full bit, BF of the SSPSTAT register, was set before the transfer was received.
- The SSP Overflow bit, SSPOV of the SSPCON register, was set before the transfer was received.
- The SSP Module is being operated in Firmware Master mode.

In such a case, the SSPSR register value is not loaded into the SSPBUF, but bit SSPIF of the PIR1 register is set. Table 17-2 shows the results of when a data transfer byte is received, given the status of bits BF and SSPOV. Flag bit BF is cleared by reading the SSPBUF register, while bit SSPOV is cleared through software.

FIGURE 17-9: START AND STOP CONDITIONS

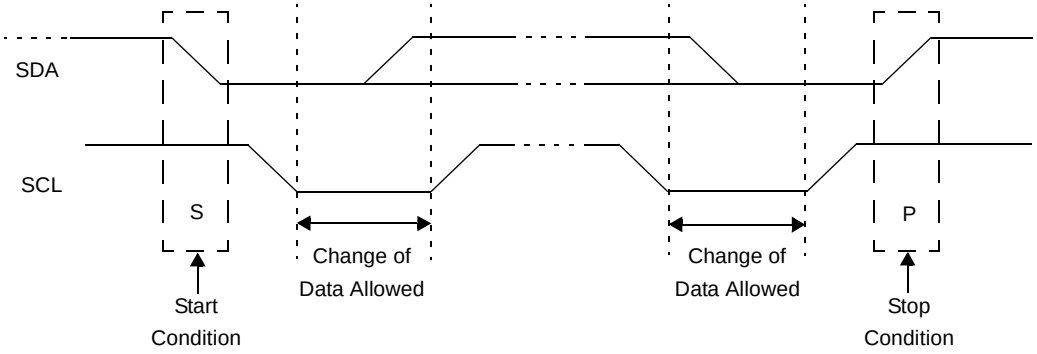


TABLE 17-2: DATA TRANSFER RECEIVED BYTE ACTIONS

Status Bits as Data Transfer is Received		SSPSR → SSPBUF	Generate $\overline{ACK}$ Pulse	Set bit SSPIF (SSP Interrupt occurs if enabled)
BF	SSPOV			
0	0	Yes	Yes	Yes
1	0	No	No	Yes
1	1	No	No	Yes
0	1	No	No	Yes

Note 1: Shaded cells show the conditions where the user software did not properly clear the overflow condition.

19.2 Wake-up Using Interrupts

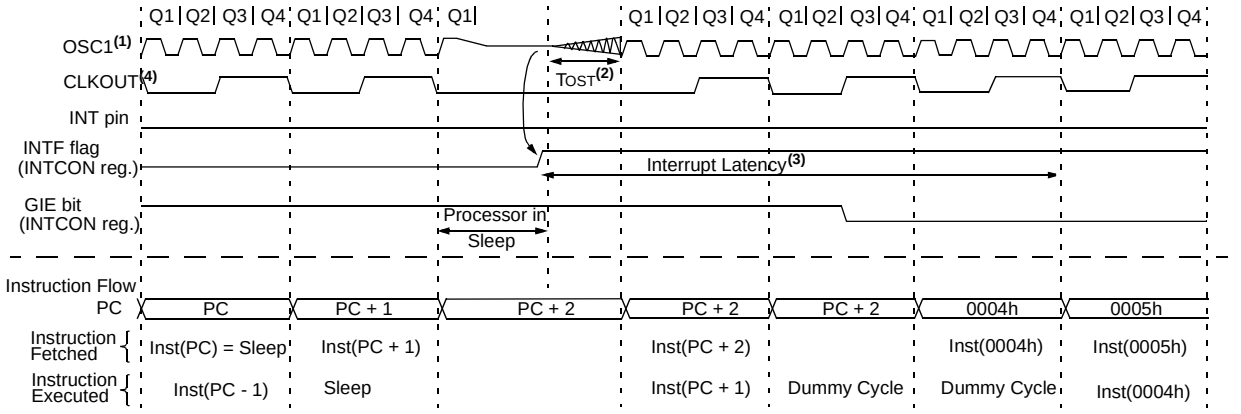
When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will not be cleared, the $\overline{TO}$ bit will not be set and the $\overline{PD}$ bit will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from Sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT prescaler and postscaler (if enabled) will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

FIGURE 19-1: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS or LP Oscillator mode assumed.
2: TOST = 1024 TOSC (drawing not to scale). This delay does not apply to EC and RC Oscillator modes.
3: GIE = 1 assumed. In this case after wake-up, the processor jumps to 0004h. If GIE = 0, execution will continue in-line.
4: CLKOUT is not available in XT, HS, LP or EC Oscillator modes, but shown here for timing reference.

TABLE 19-1: SUMMARY OF REGISTERS ASSOCIATED WITH POWER-DOWN MODE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
IOCB	IOCB7	IOCB6	IOCB5	IOCB4	IOCB3	IOCB2	IOCB1	IOCB0	0000 0000	0000 0000
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 0000	0000 0000
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIE2	—	—	—	—	—	—	—	CCP2IE	---- ---0	---- ---0
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIR2	—	—	—	—	—	—	—	CCP2IF	---- ---0	---- ---0

Legend: x = unknown, u = unchanged, – = unimplemented, read as '0'. Shaded cells are not used in Power-Down mode.

22.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

22.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

22.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

22.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

23.2 DC Characteristics: PIC16(L)F722/3/4/6/7-I/E (Industrial, Extended)

PIC16LF722/3/4/6/7			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC16F722/3/4/6/7			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Device Characteristics**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**	
						VDD	**Note**
	Supply Current (IDD)(1, 2)						
D009	LDO Regulator	—	350	—	µA	—	HS, EC OR INTOSC/INTOSCIO (8-16 MHz) Clock modes with all VCAP pins disabled
		—	50	—	µA	—	All VCAP pins disabled
		—	30	—	µA	—	VCAP enabled on RA0, RA5 or RA6
		—	5	—	µA	—	LP Clock mode and Sleep (requires FVR and BOR to be disabled)
D010		—	7.0	12	µA	1.8	FOSC = 32 kHz LP Oscillator mode **(Note 4)**, -40°C ≤ TA ≤ +85°C
		—	9.0	14	µA	3.0	
D010		—	11	20	µA	1.8	FOSC = 32 kHz LP Oscillator mode **(Note 4)**, -40°C ≤ TA ≤ +85°C
		—	14	22	µA	3.0	
		—	15	24	µA	5.0	
D011		—	7.0	12	µA	1.8	FOSC = 32 kHz LP Oscillator mode -40°C ≤ TA ≤ +125°C
		—	9.0	18	µA	3.0	
D011		—	11	21	µA	1.8	FOSC = 32 kHz LP Oscillator mode **(Note 4)** -40°C ≤ TA ≤ +125°C
		—	14	25	µA	3.0	
		—	15	27	µA	5.0	
D011		—	110	150	µA	1.8	FOSC = 1 MHz XT Oscillator mode
		—	150	215	µA	3.0	
D011		—	120	175	µA	1.8	FOSC = 1 MHz XT Oscillator mode **(Note 5)**
		—	180	250	µA	3.0	
		—	240	300	µA	5.0	
D012		—	230	300	µA	1.8	FOSC = 4 MHz XT Oscillator mode
		—	400	600	µA	3.0	
D012		—	250	350	µA	1.8	FOSC = 4 MHz XT Oscillator mode **(Note 5)**
		—	420	650	µA	3.0	
		—	500	750	µA	5.0	
D013		—	125	180	µA	1.8	FOSC = 1 MHz EC Oscillator mode
		—	230	270	µA	3.0	
D013		—	150	205	µA	1.8	FOSC = 1 MHz EC Oscillator mode **(Note 5)**
		—	225	320	µA	3.0	
		—	250	410	µA	5.0	

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; MCLR = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.

4: FVR and BOR are disabled.

5: 0.1 µF capacitor on VCAP (RA0).

FIGURE 24-25: PIC16F722/3/4/6/7 TYPICAL IDD vs. FOSC OVER VDD, INTOSC MODE, VCAP = 0.1 µF

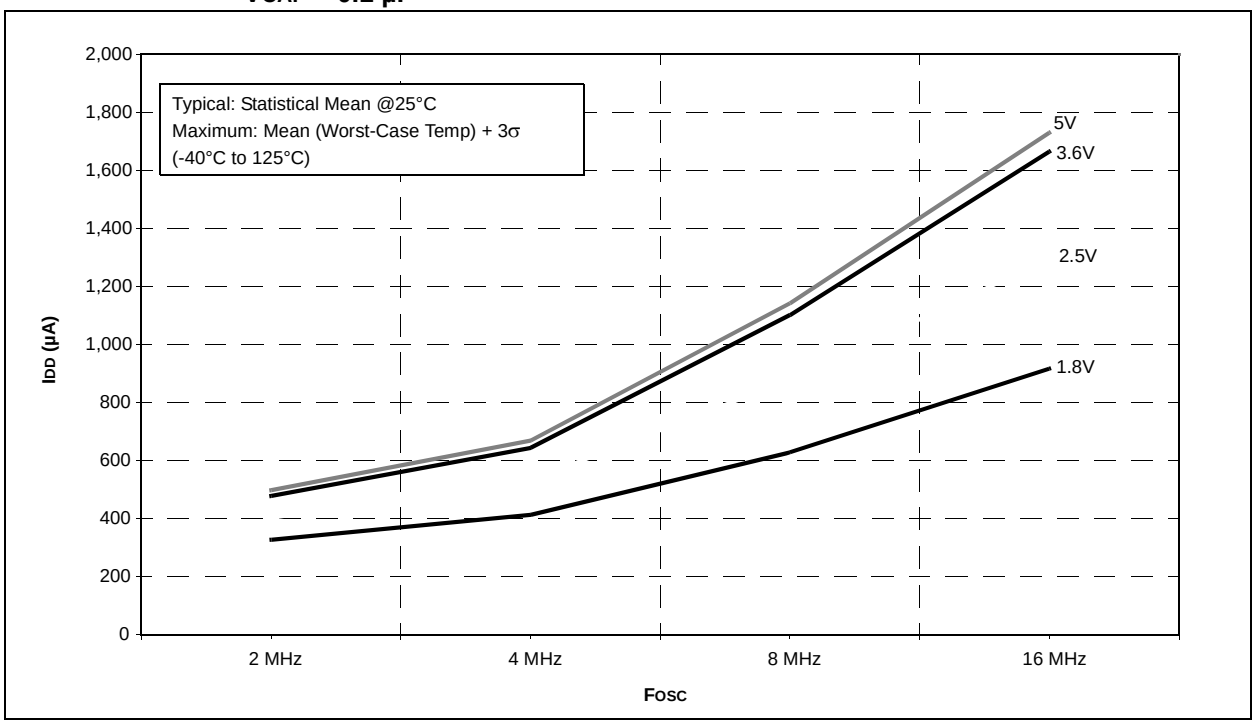


FIGURE 24-26: PIC16LF722/3/4/6/7 TYPICAL IDD vs. FOSC OVER VDD, INTOSC MODE

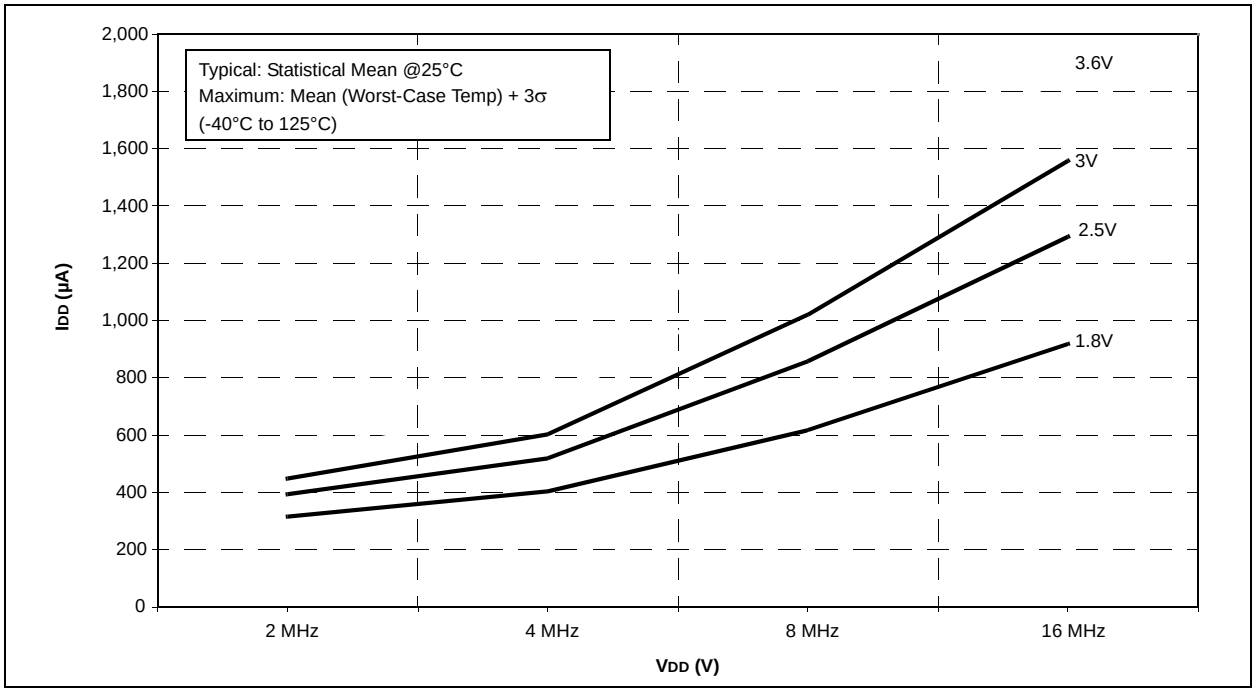


FIGURE 24-27: PIC16F722/3/4/6/7 MAXIMUM BASE I_{PD} vs. V_{DD}, V_{CAP} = 0.1 µF

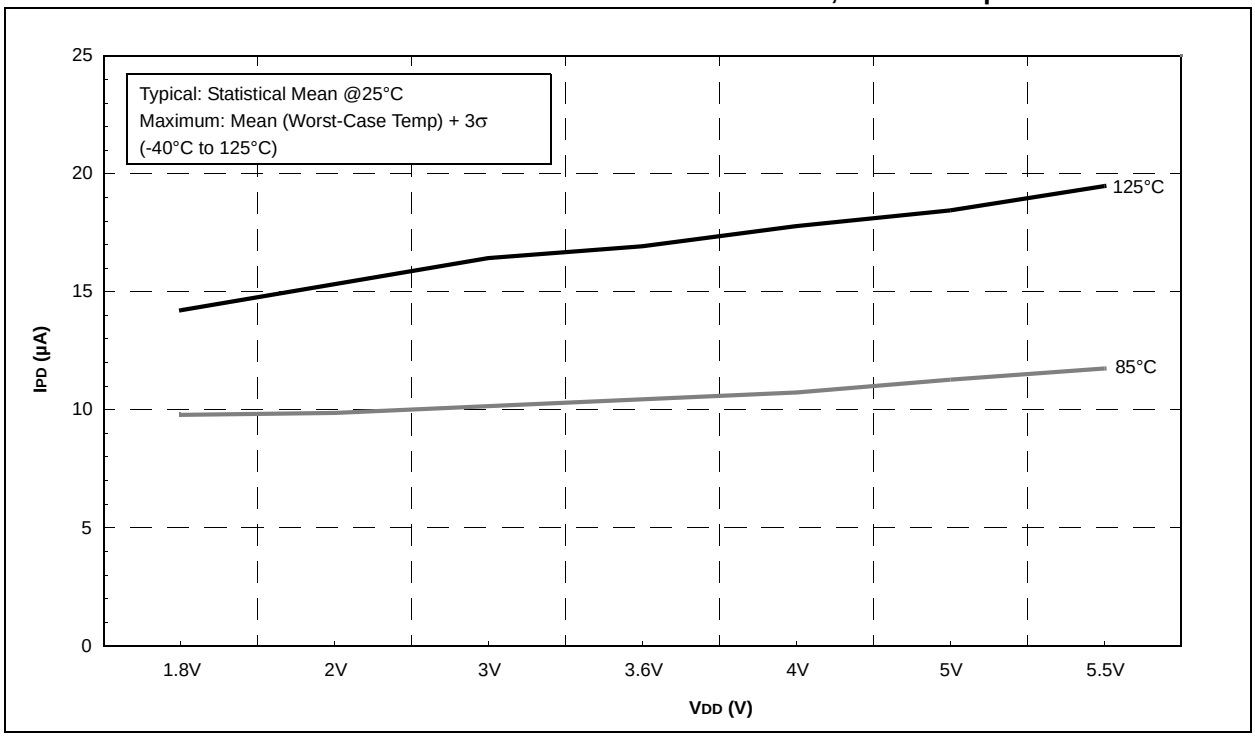


FIGURE 24-28: PIC16LF722/3/4/6/7 MAXIMUM BASE I_{PD} vs. V_{DD}

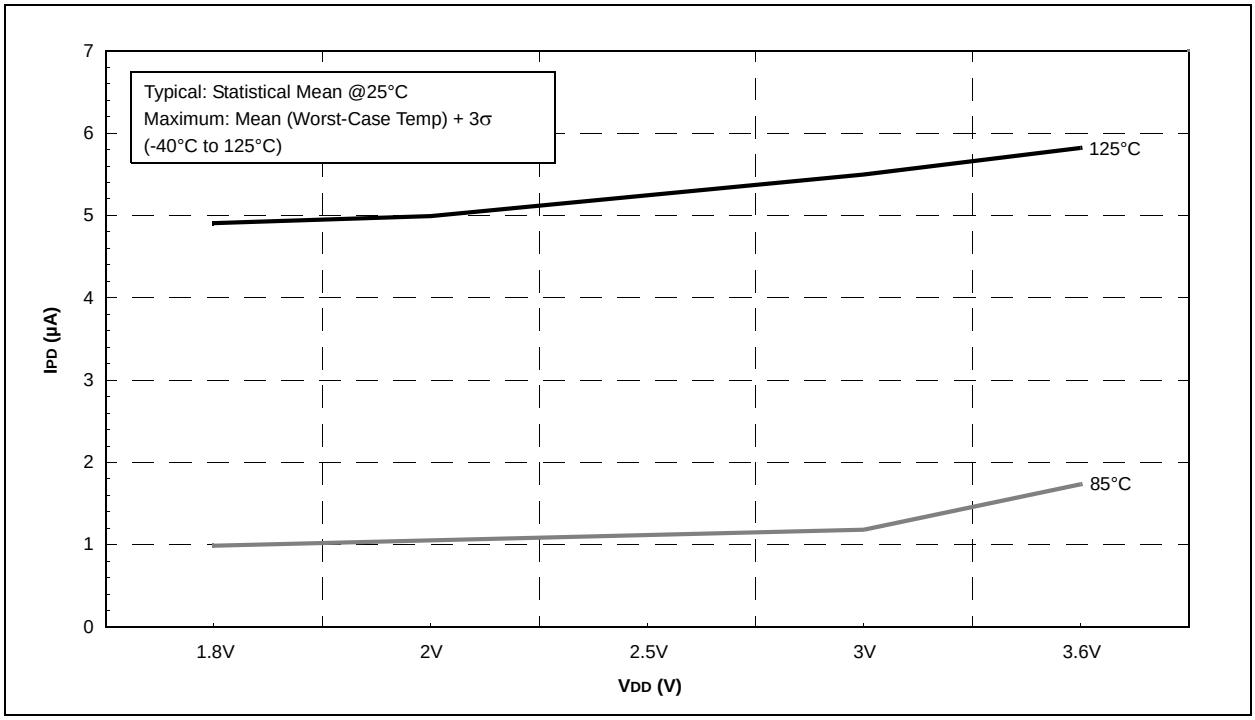


FIGURE 24-31: PIC16F722/3/4/6/7 FIXED VOLTAGE REFERENCE IPD VS. VDD, VCAP = 0.1 µF

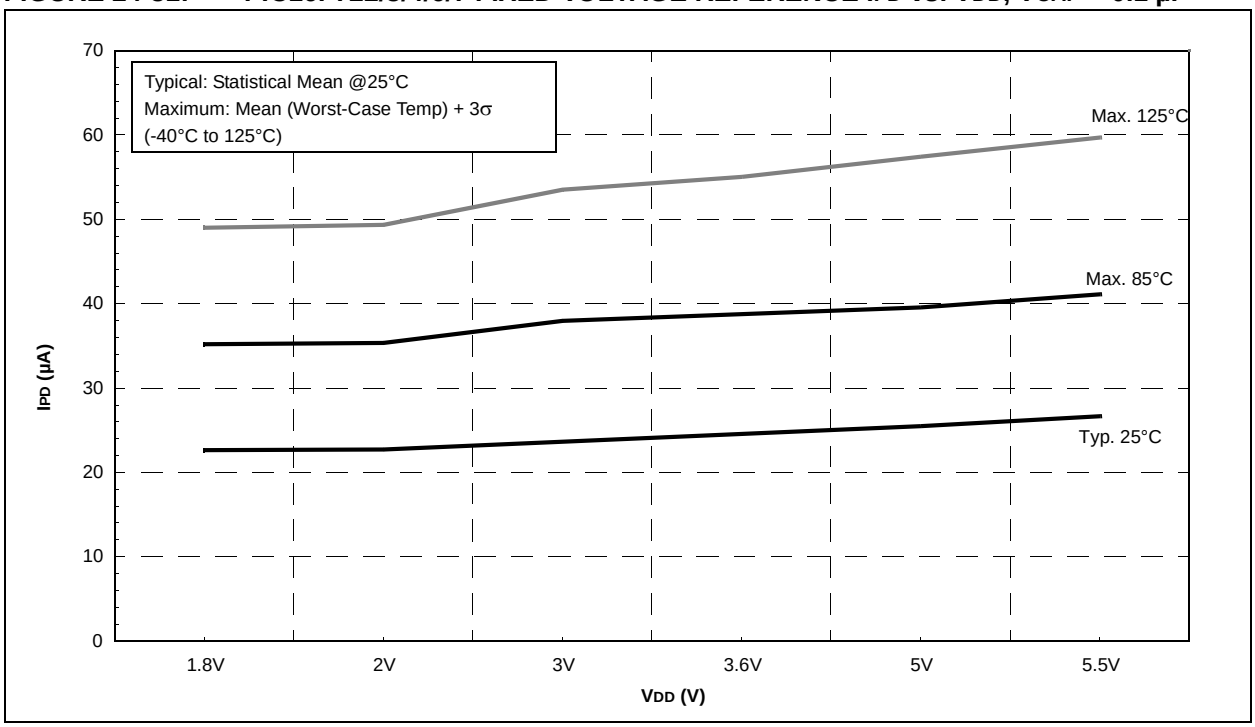


FIGURE 24-32: PIC16LF722/3/4/6/7 FIXED VOLTAGE REFERENCE IPD VS. VDD

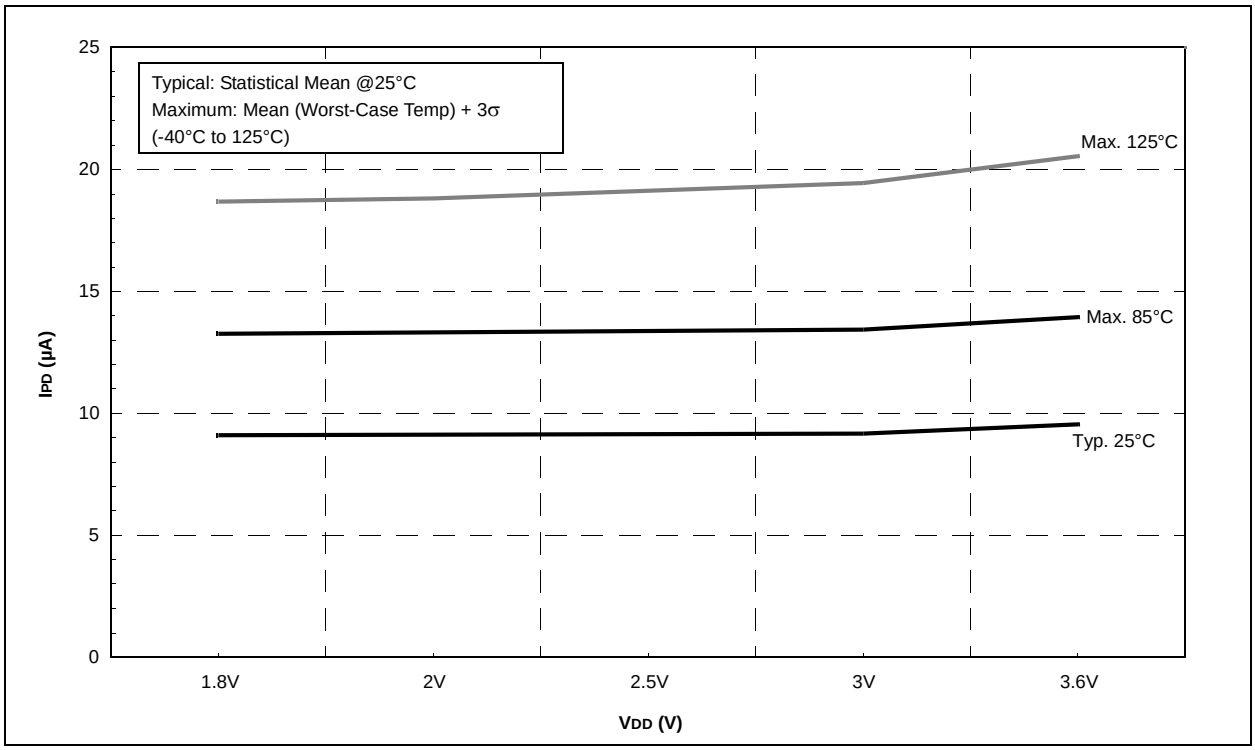


FIGURE 24-35: PIC16F722/3/4/6/7 CAP SENSE HIGH POWER IPD vs. VDD, VCAP = 0.1 µF

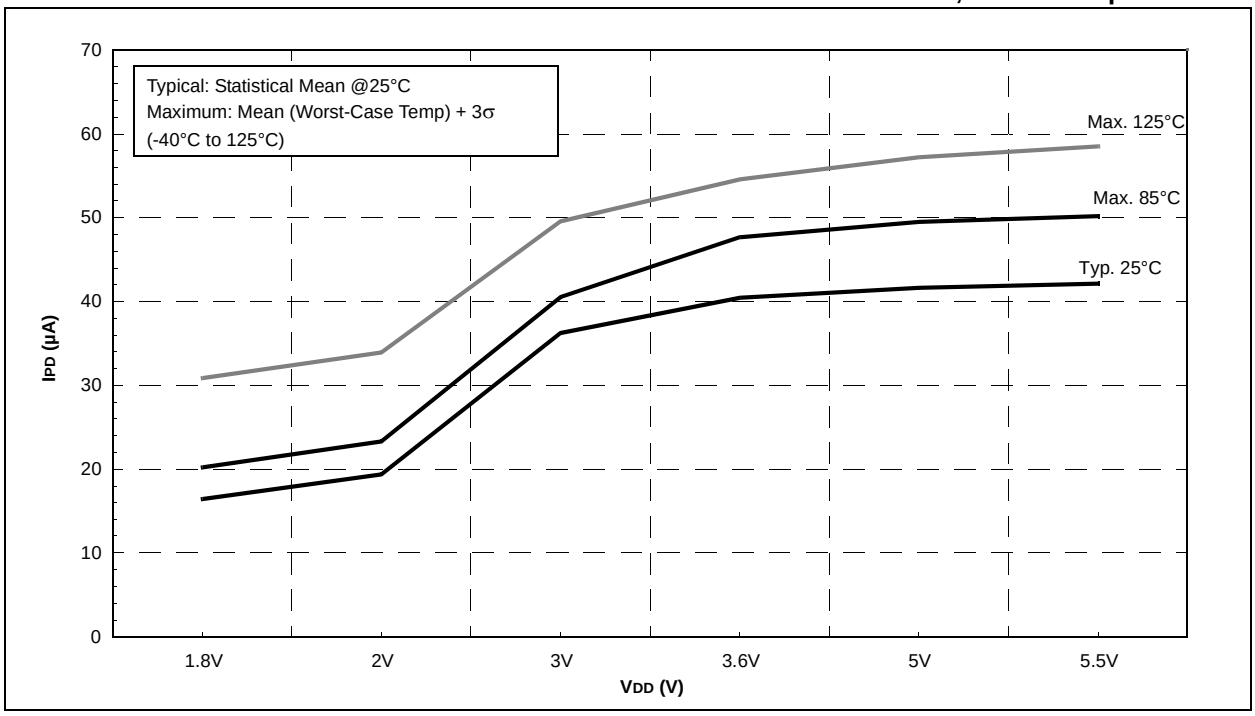


FIGURE 24-36: PIC16LF722/3/4/6/7 CAP SENSE HIGH POWER IPD vs. VDD

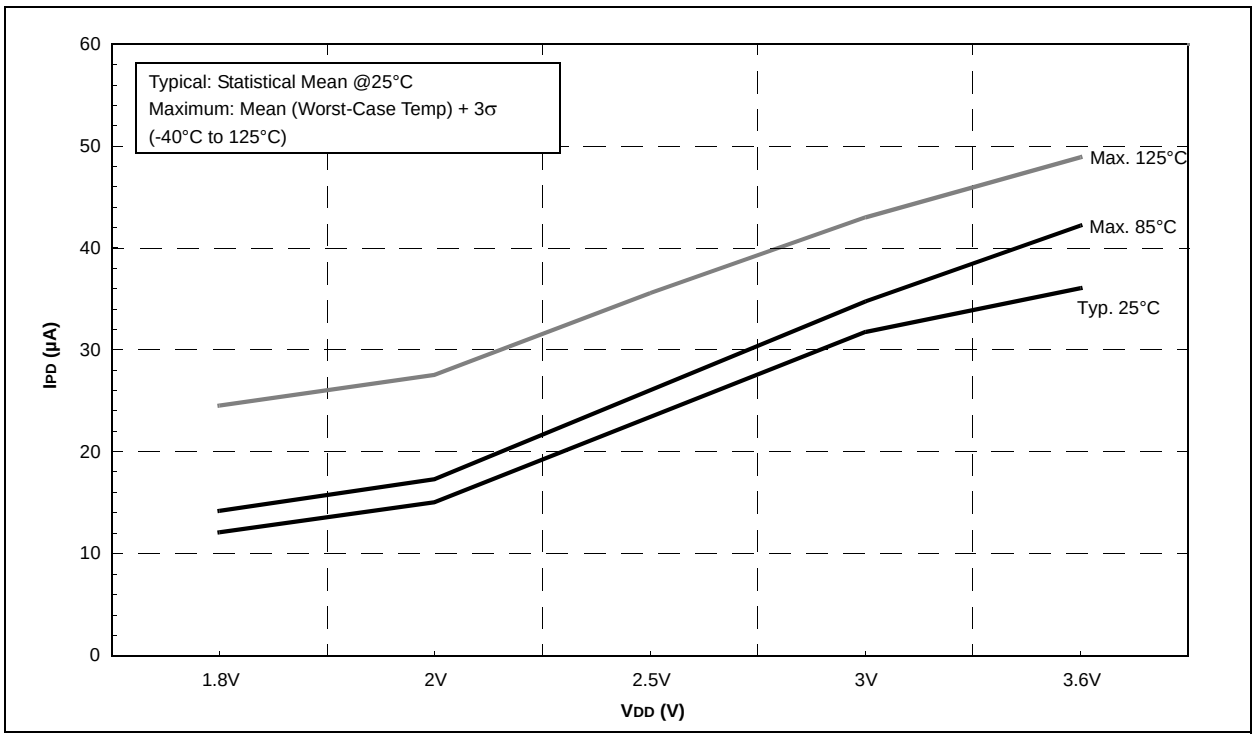


FIGURE 24-59: PIC16F722/3/4/6/7 WDT TIME-OUT PERIOD

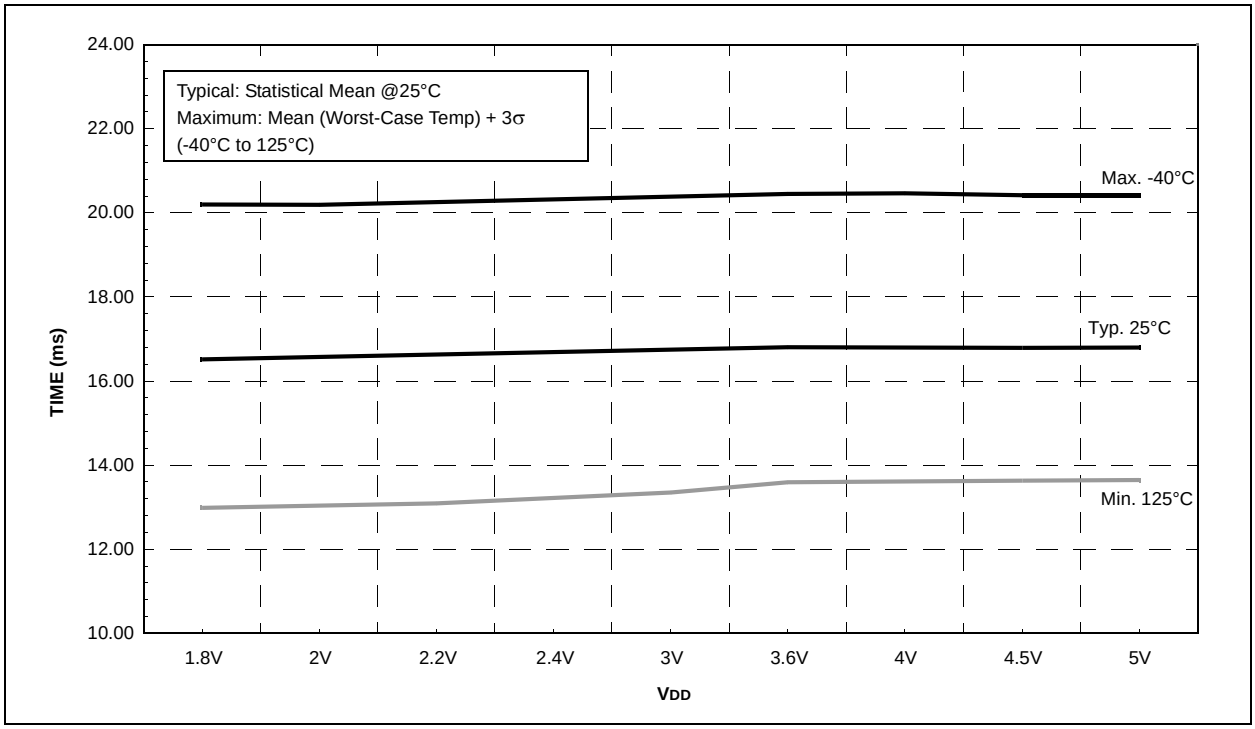
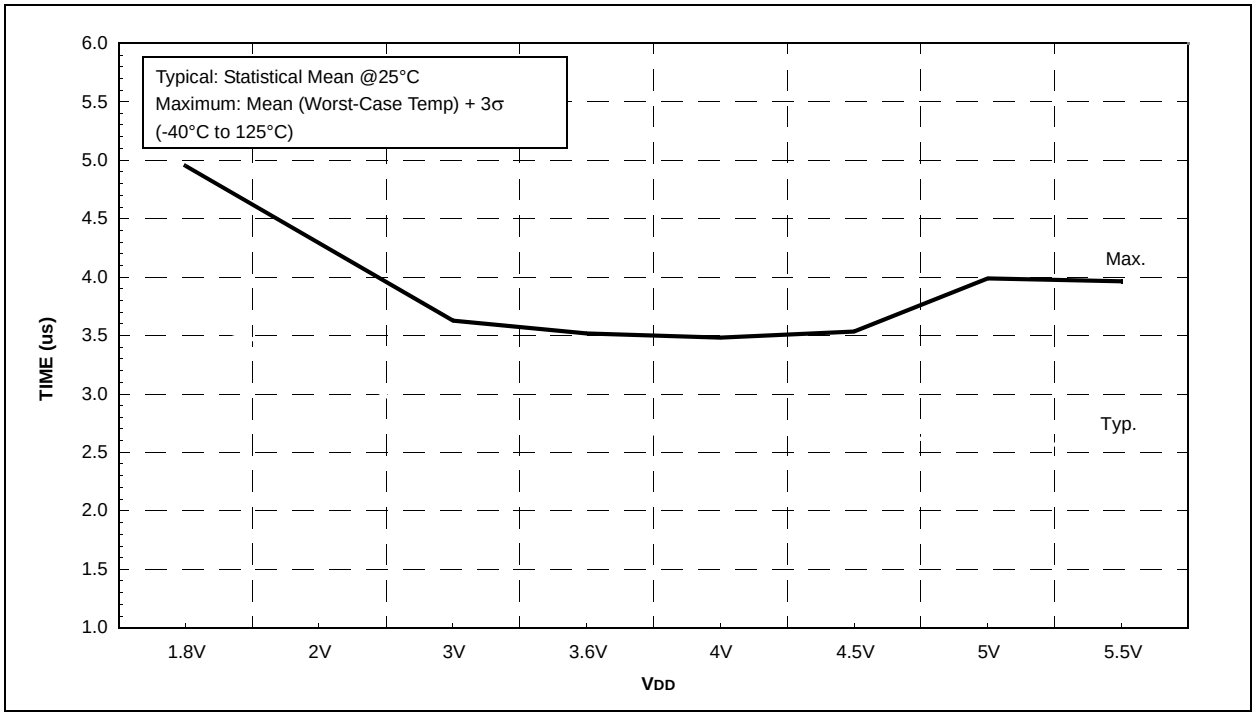
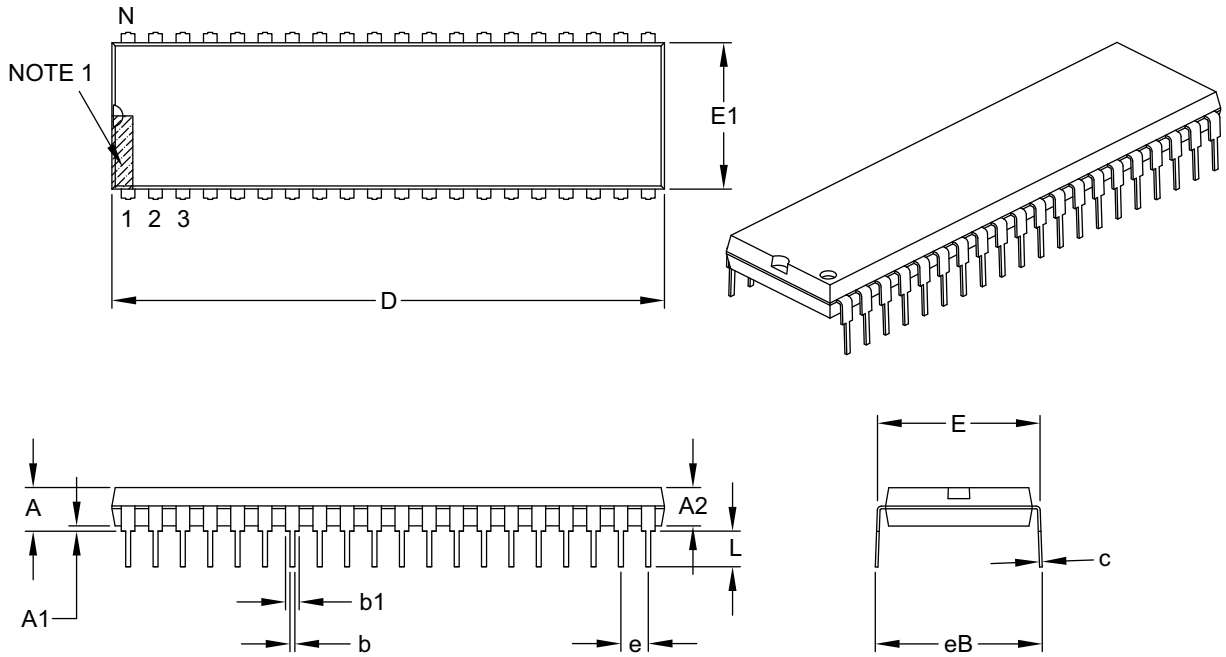


FIGURE 24-60: PIC16F722/3/4/6/7 HFINTOSC WAKE-UP FROM SLEEP START-UP TIME



40-Lead Plastic Dual In-Line (P) – 600 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		40	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.250
Molded Package Thickness	A2	.125	–	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.590	–	.625
Molded Package Width	E1	.485	–	.580
Overall Length	D	1.980	–	2.095
Tip to Seating Plane	L	.115	–	.200
Lead Thickness	c	.008	–	.015
Upper Lead Width	b1	.030	–	.070
Lower Lead Width	b	.014	–	.023
Overall Row Spacing §	eB	–	–	.700

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-016B

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (12/2007)

Original release.

Revision B (08/2008)

Electrical Specification updates; Package Drawings; miscellaneous updates.

Revision C (04/2009)

Revised data sheet title; Revised Low-Power Features section; Revised Section 6.2.2.4 RA3/AN3/VREF; Revised Figure 16-8 Synchronous Reception.

Revision D (07/2009)

Removed the Preliminary Label; Updated the “Electrical Characteristics” section; Added charts in the “Char. Data” section; Deleted “Based 8-Bit CMOS” from title; Updated the “Special Microcontroller Features” section and the “Peripheral Features” section; Changed the title of the “Low Power Features” section into “Extreme Low-Power Management PIC16LF72X with nanoWatt XLP” and updated this section; Inserted new section – “Analog Features” (page 1); Changed the title of the “Peripheral Features” section into “Peripheral Highlights” and updated the section.

Revision E (10/2009)

Added paragraph to section 5.0 (LDO Voltage Regulator); Updated the Electrical Specifications section (Added another absolute Maximum Rating; Updated section 23.1 and Table 23-4); Updated the Pin Diagrams with the UQFN package; Updated Table 1, adding UQFN; Updated section 23.5 (Thermal Considerations); Updated the Packaging Information section adding the UQFN Package; Updated the Product Identification System section.

Revision F (12/2015)

Updated Table 2; Updated 23.1, 23.3 and 9.2.4 Sections; Updated Figure 23-9; Other minor corrections.

APPENDIX B: MIGRATING FROM OTHER PIC® DEVICES

This discusses some of the issues in migrating from other PIC® devices to the PIC16F72X family of devices.

B.1 PIC16F77 to PIC16F72X

TABLE B-1: FEATURE COMPARISON

Feature	PIC16F77	PIC16F727
Max. Operating Speed	20 MHz	20 MHz
Max. Program Memory (Words)	8K	8K
Max. SRAM (Bytes)	368	368
A/D Resolution	8-bit	8-bit
Timers (8/16-bit)	2/1	2/1
Oscillator Modes	4	8
Brown-out Reset	Y	Y
Internal Pull-ups	RB<7:0>	RB<7:0>
Interrupt-on-change	RB<7:4>	RB<7:0>
Comparator	0	0
USART	Y	Y
Extended WDT	N	N
Software Control Option of WDT/BOR	N	N
INTOSC Frequencies	None	500 kHz - 16 MHz
Clock Switching	N	N